

# ***TCT a tool to investigate silicon detectors***

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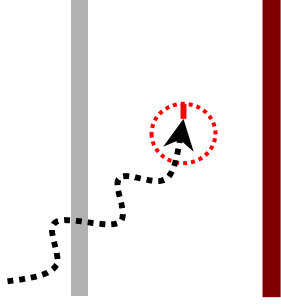
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*(on leave from Jozef Stefan Institute, Ljubljana, Slovenia)*

- Basics of signal formation in silicon detectors
- TCT setup components and data analysis
- What can be measured with TCT and how it is done?
- Conclusions

# Charge generation in silicon detector

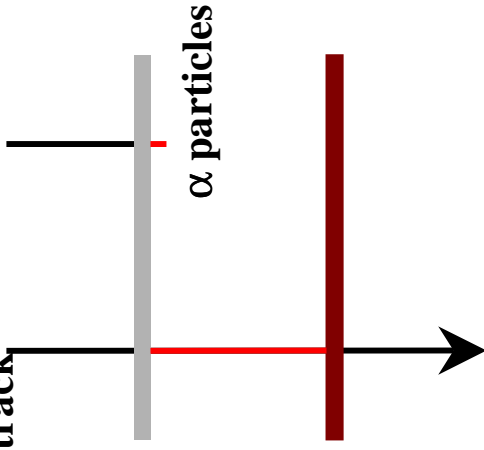
single  $\gamma$  generation ( $E_\gamma < 1 \text{ MeV}$ )  
(photoeffect, compton)



**x-ray imaging**

- deposition of e-h pairs at the point of conversion

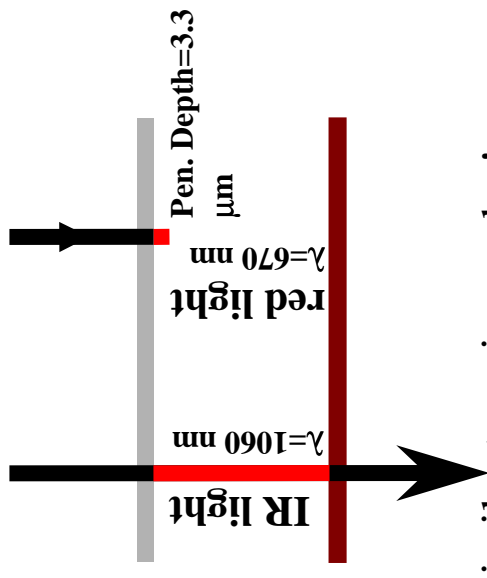
ionizing particle track



interested in m.i.p.:

- deposition of e-h pairs along the track
- most probable E loss 22500 e-h in  $300 \mu\text{m}$
- usually detected by charge sensitive preamplifiers

laser light generation  
( $\sim \text{UV-IR}(1060 \text{ nm})$ )



Similar to m.i.p. and  $\alpha$ !

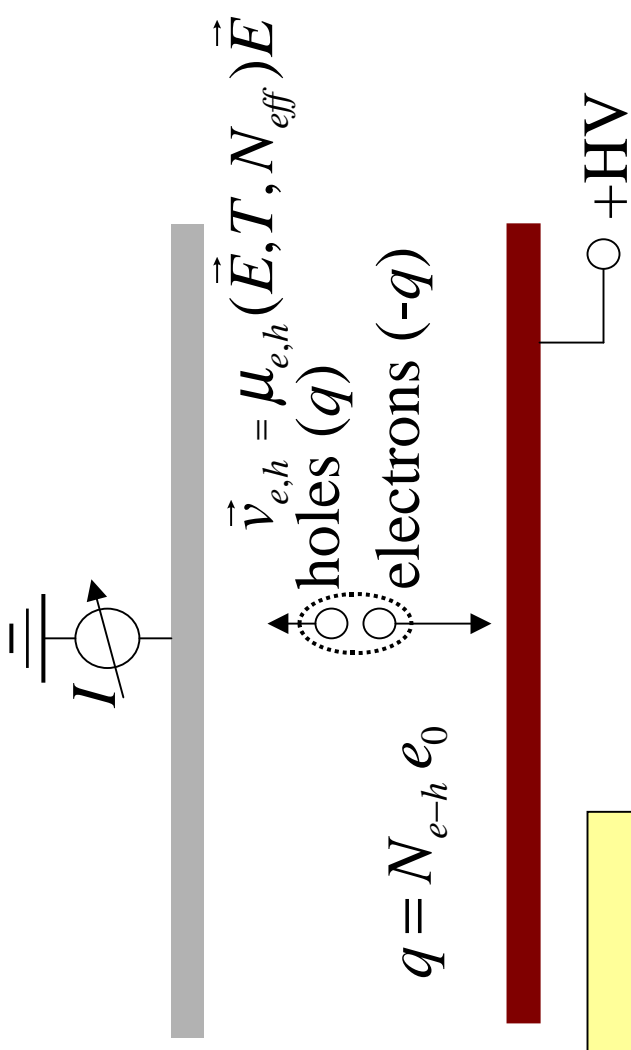
- a short pulse is required ( $\sim 1 \text{ ns}$ )
- the amount of the deposited charge can be varied
- exponential deposition profile (depth can be varied with  $\lambda$ )
- much wider deposition area

# Induced current due to charge drift

The induced current

depends on:

- trapping of the  $q$
- weighting field
- drift velocity



$$I_{e,h}(t) = -q \vec{E}_w \cdot \vec{v}_{e,h}(t)$$

$$I(t) = I_e(t) + I_h(t)$$

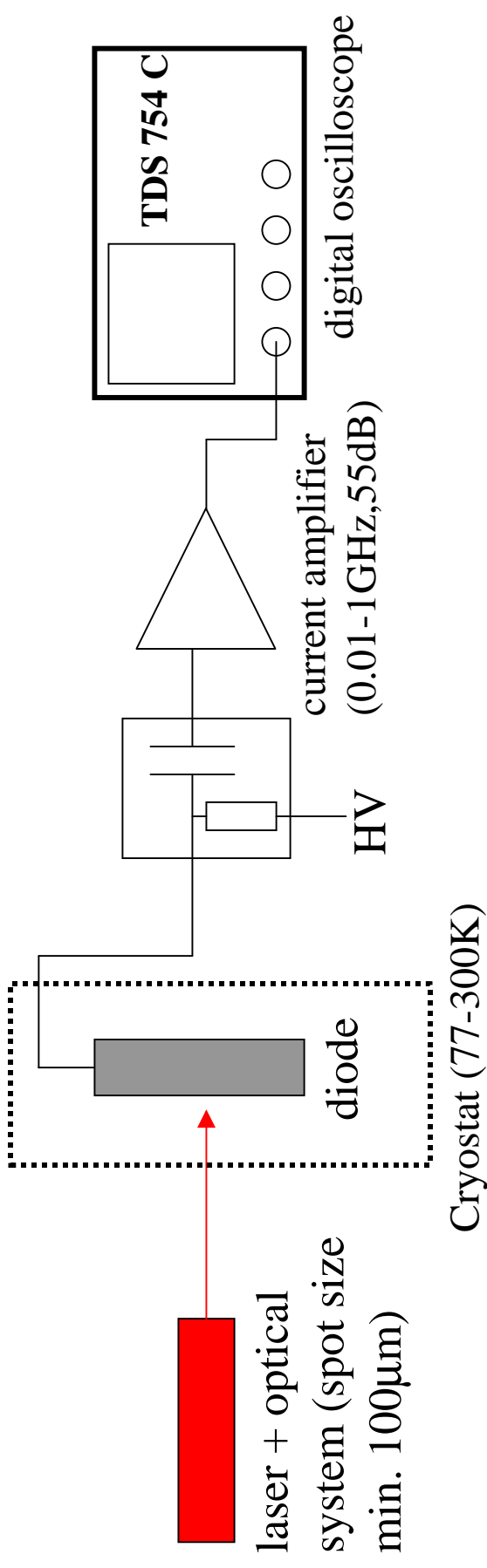
$$Q = \int I(t) dt = Q_e + Q_h$$

depend on creation point

charge induced by m.i.p. :

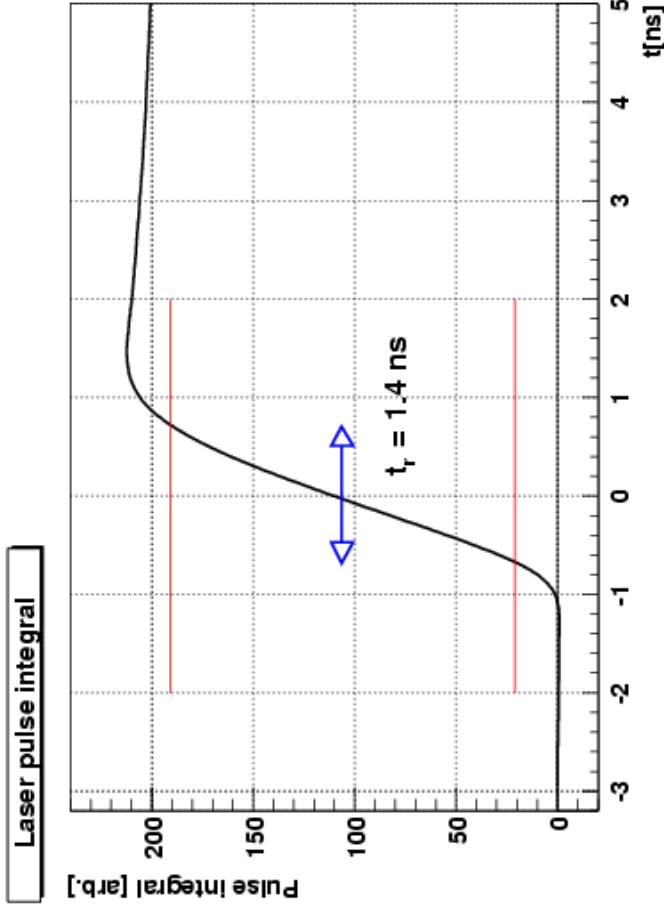
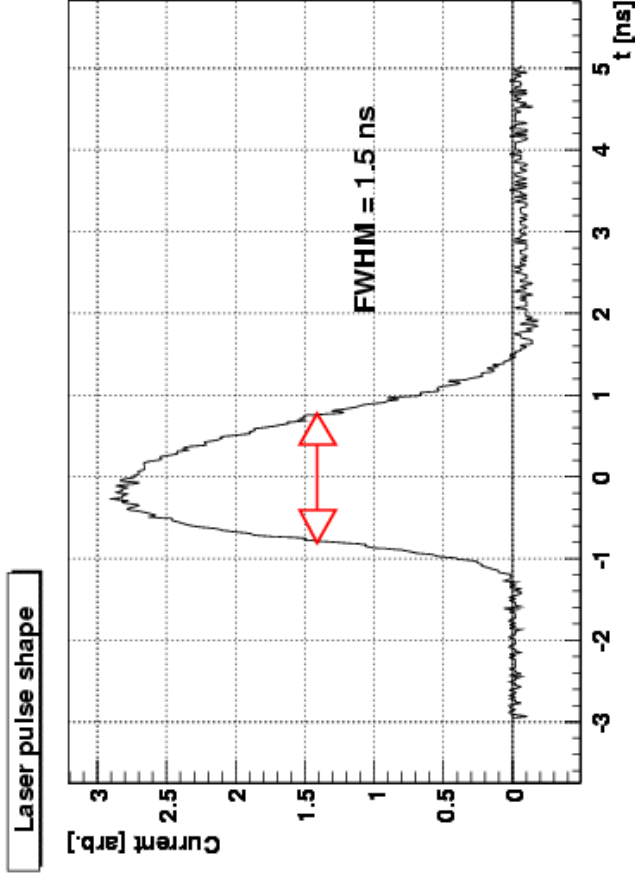
$$I^{mip}(t) = \sum_{pairs} I_e(t) + I_h(t)$$

## TCT set-up



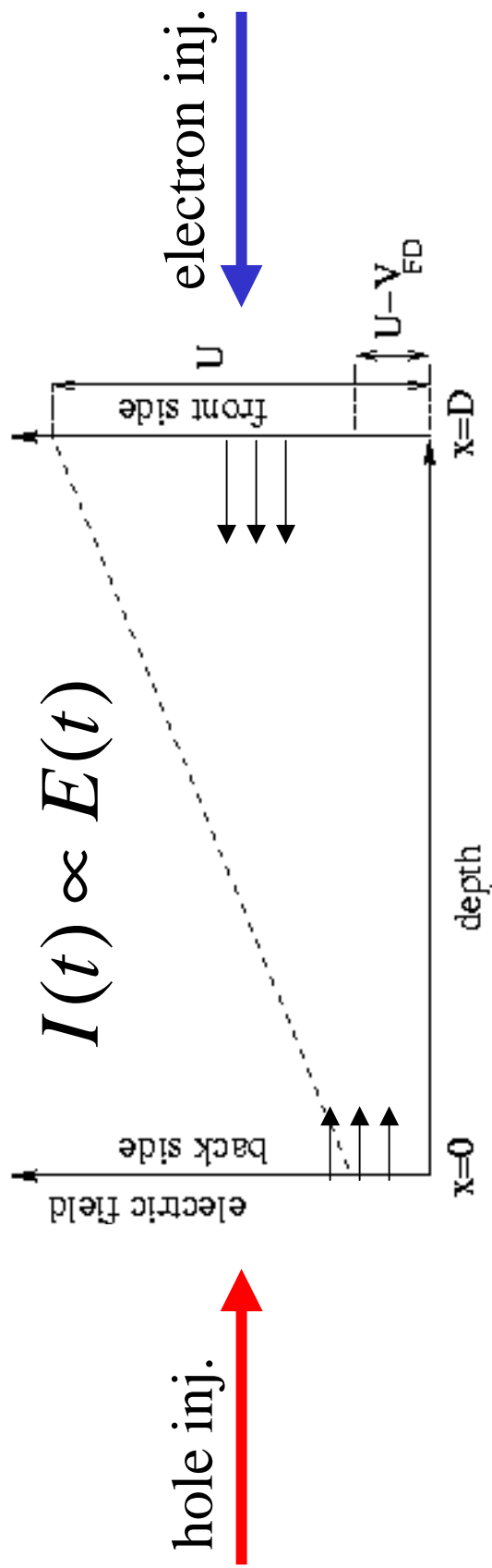
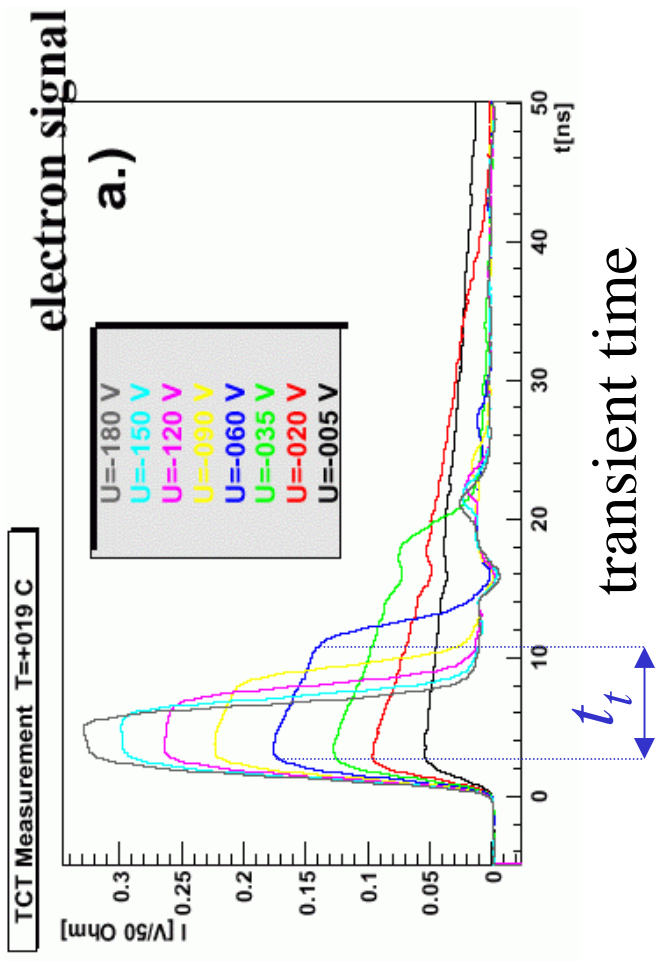
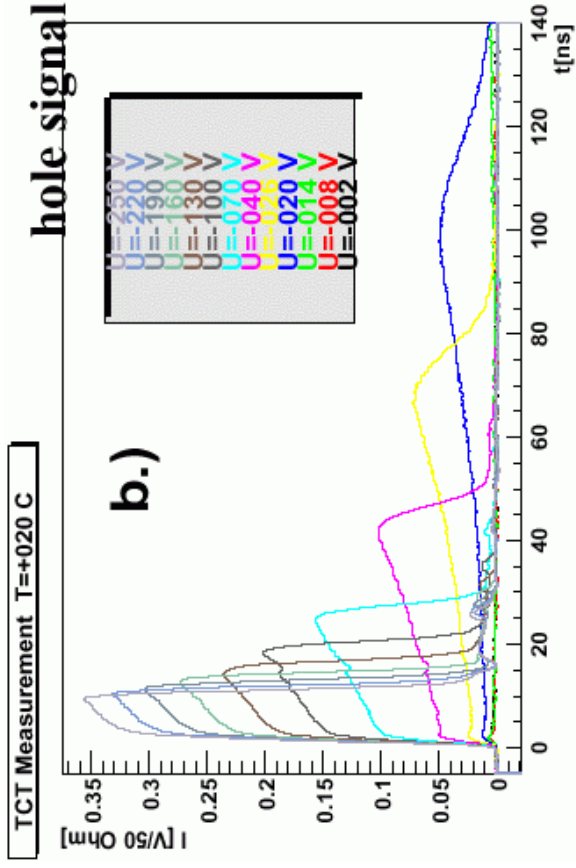
- light pulse repetition rate ( can be set from  $10^{-3}$  - 400k Hz )
- intensity of the light pulse can be tuned to charge equivalent from:
  - few mip ( $5 \cdot 10^5$  electron-hole pairs/pulse) to few 100 mip
- samples have hole in metalization (p<sup>+</sup> contact) or mesh metalization (n<sup>+</sup> contact)
- an LN<sub>2</sub> pour fill optical cryostat used for cooling the samples

# TCT set-up (laser pulse)



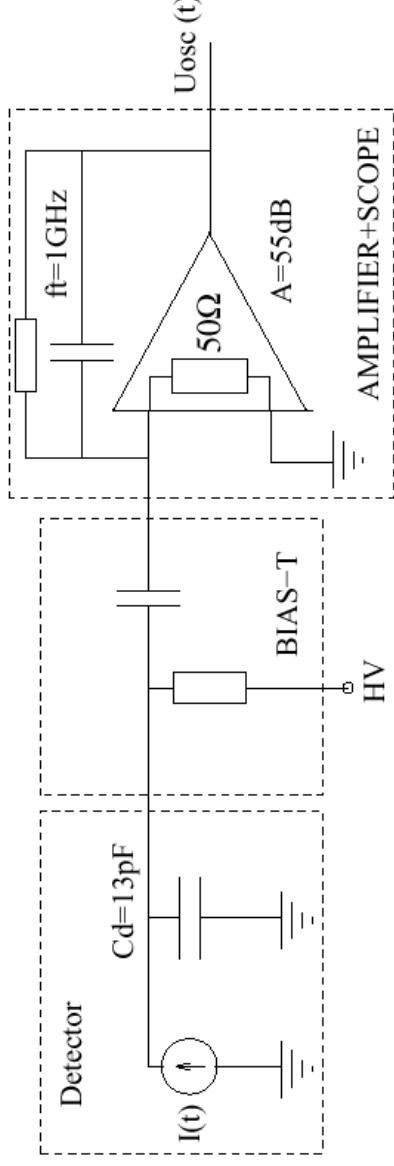
Measured with fast photo-diode!

# Understanding TCT signal



# I. Processing of the TCT signal

electronic transfer function ( $C_d, R_{osc}$ )  
 impedance matching - reflections

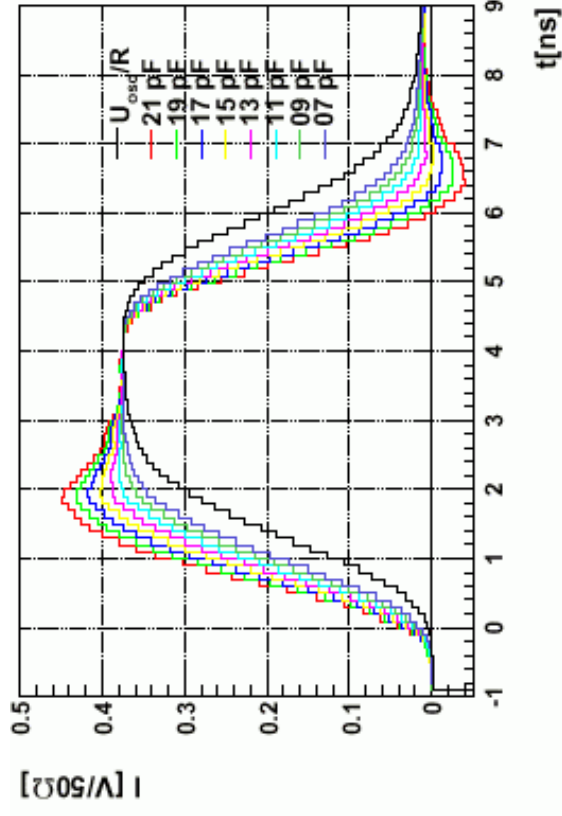
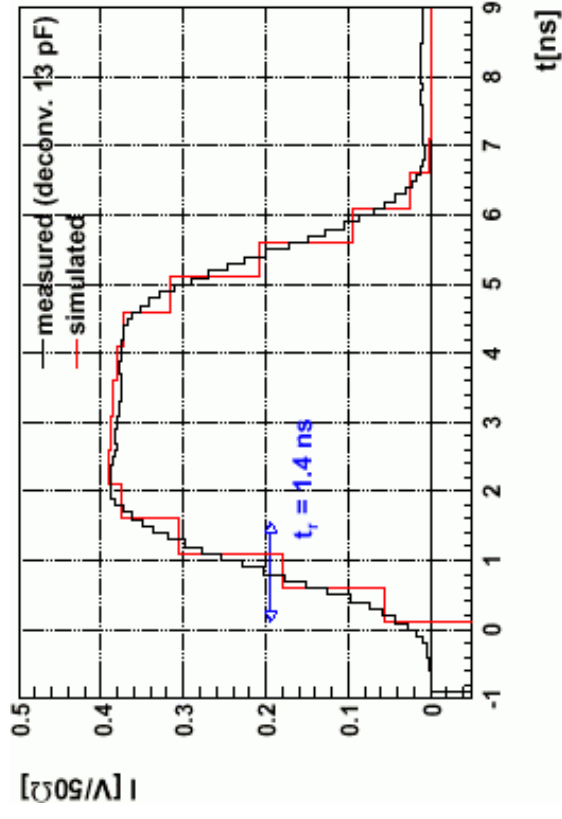


equivalent to RC cir.

$$I(t) = \frac{\tau}{R} \frac{dU_{osc}(t)}{dt} + \frac{R}{U_{osc}(t)}$$

$$\tau = R_{osc} C_d \approx 500 \text{ ps}$$

$$\frac{1}{2\pi \tau} < f_t, C_{dec} \gg C_d$$



## II. Processing of the TCT signal

finite duration of laser pulse

$$I_m(t) = \int P(x) I_t(t-x) dx$$

measured

laser pulse profile

desired

solution e.g. by using Fourier Transform

$$FT(I_m) = FT(P) \cdot FT(I_t)$$

$$\downarrow$$
$$I_t(t) = FT^{-1} \left( \frac{FT(I_m)}{FT(P)} \right)$$



## Main purpose of TCT:

### Study of radiation damage on silicon detectors!

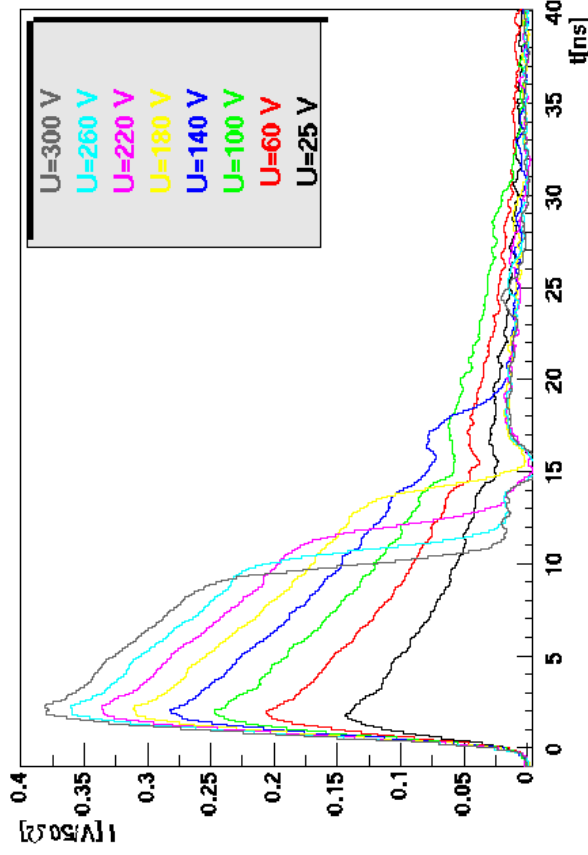
- Increase of  $N_{\text{eff}}$  and by that  $V_{\text{FD}}$ !
- Loss of the drifting charge due to trapping !
- Increase of leakage current  $I = \alpha \Phi_{\text{eq}}$  !

## What can be measured with TCT?

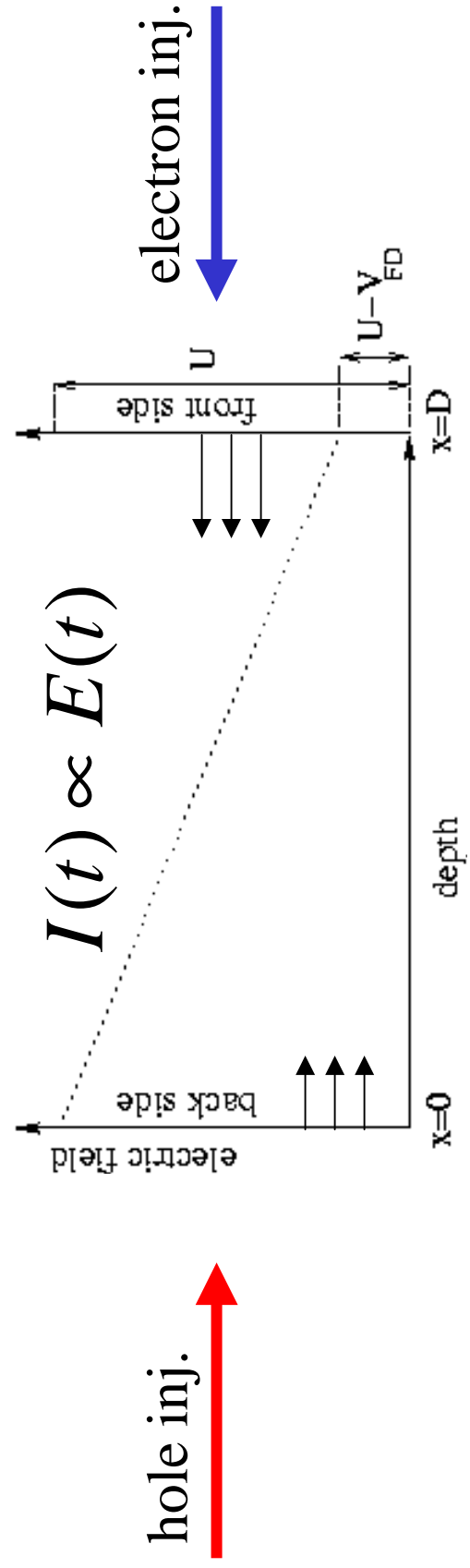
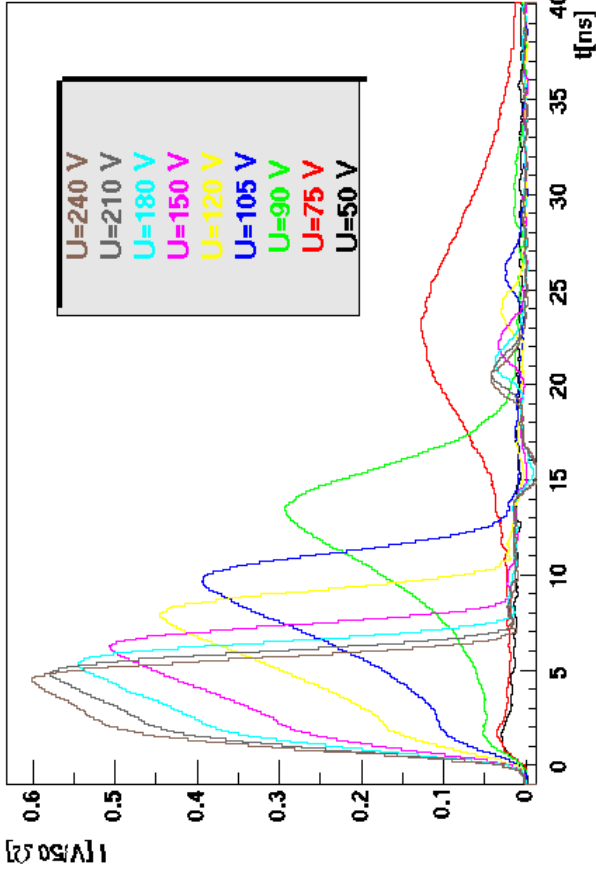
- sign of the space charge in detector bulk
- full depletion voltage (CV)
- trapping time constants (charge collection efficiency) (DLTS)
- electric field (dopant) profile in the detector (CV?)
- de-trapping time constants (DLTS, TSC)
- charge collection studies in segmented devices

# Sign of the space charge inversion

TCT Measurement @ T=+20 C



TCT Measurement @ T=+20 C



## IIa. Full depletion voltage determination

- $V_{FD}$  can be extracted from IR laser
- $V_{FD}$  can be extracted from both electron and hole signal

In both cases: from evolution induced charge as a function of voltage!

$$\int_{t_0}^{t_1} I(t) dt = Q \quad \Rightarrow \quad Q(U) \quad \text{:also called QV method}$$

$$\frac{d}{D} = \sqrt{\frac{U}{V_{FD}}}, \quad |N_{eff}| = \frac{2\epsilon_0 \epsilon V_{FD}}{e_0 D^2}$$

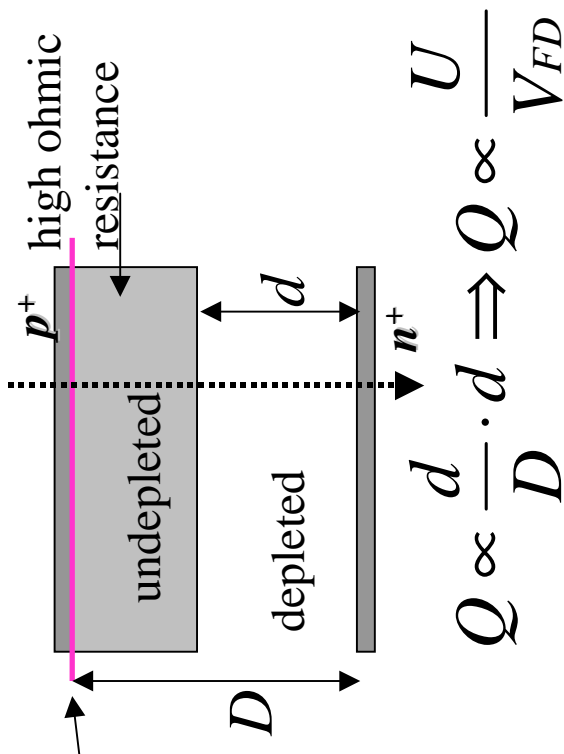
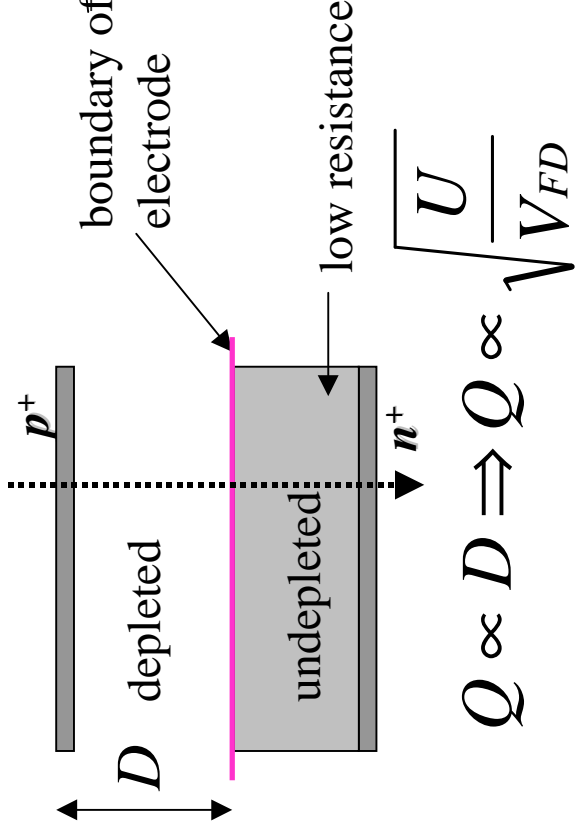
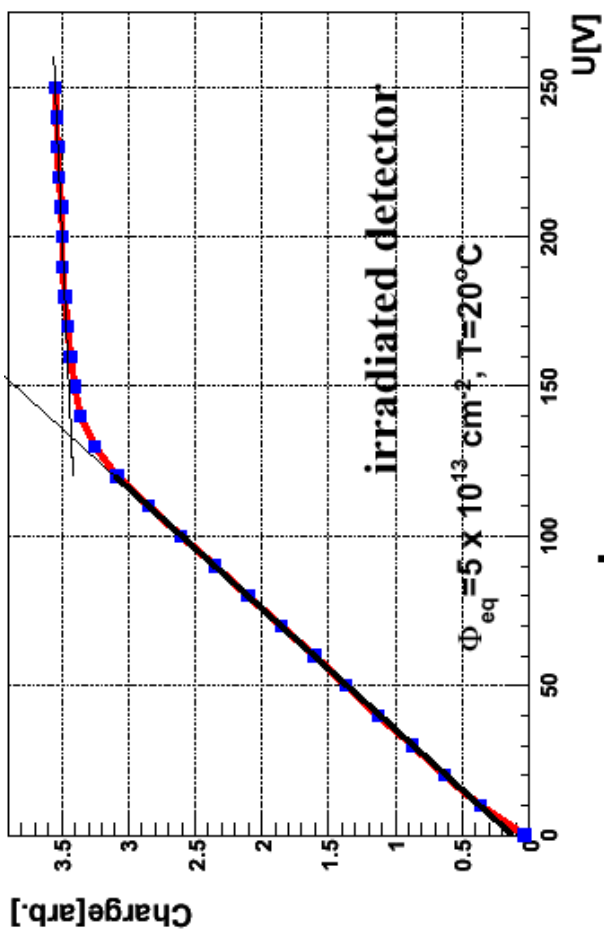
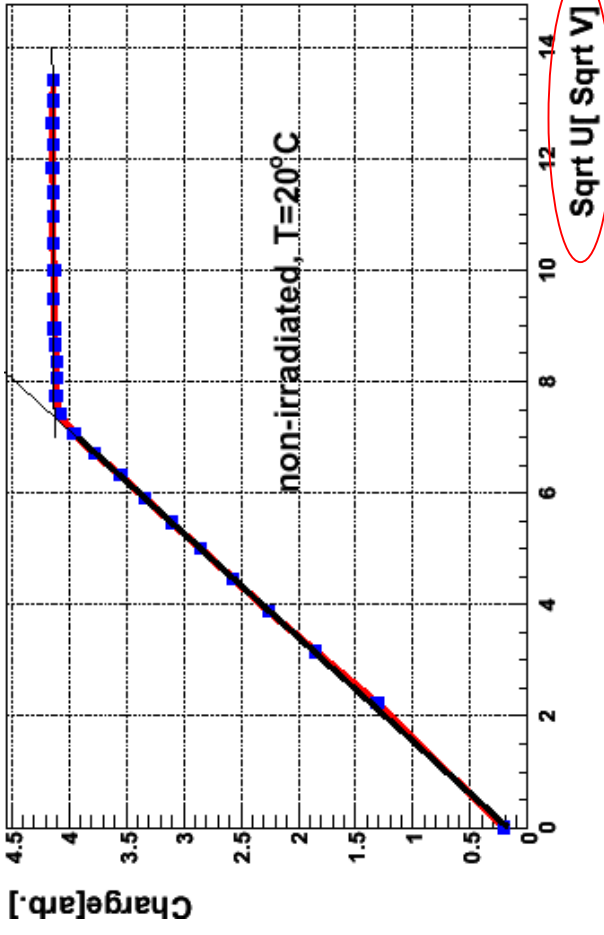
$N_{eff}(\vec{r}) = const.$   
(before irradiation)

$N_{eff}(\vec{r}) \approx const. ???$   
(after irradiation)

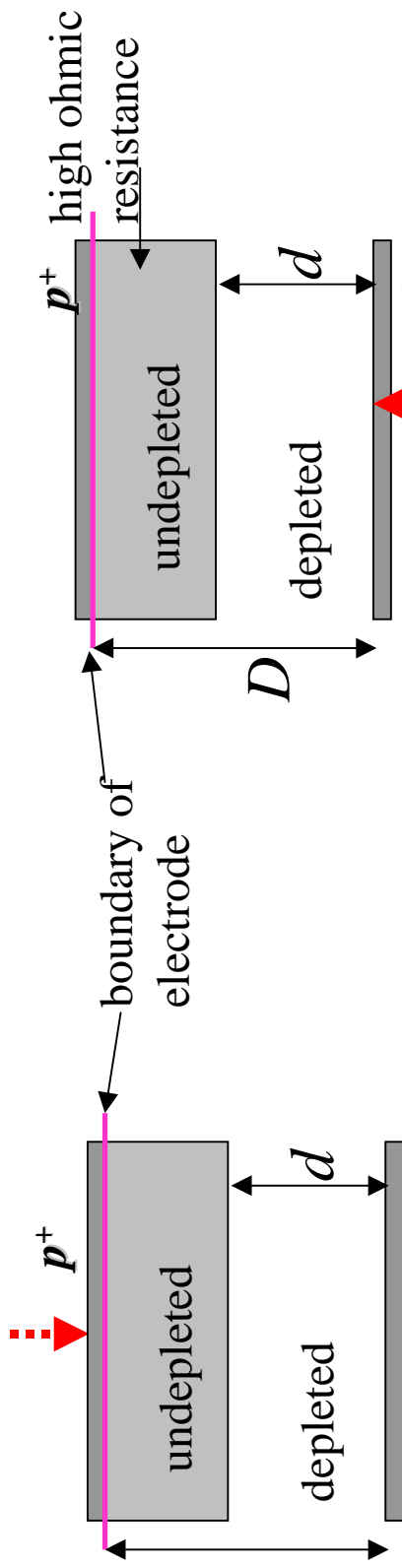
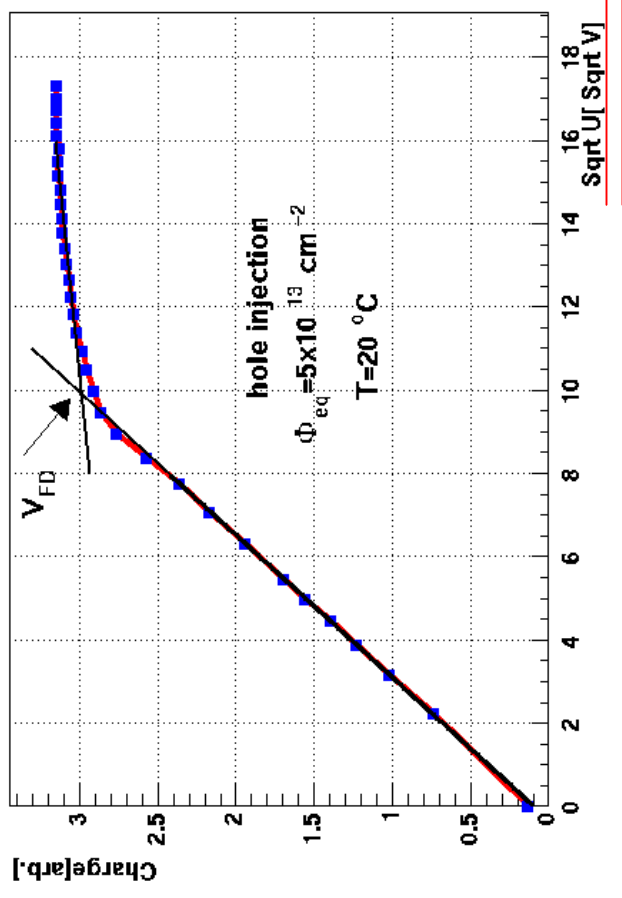
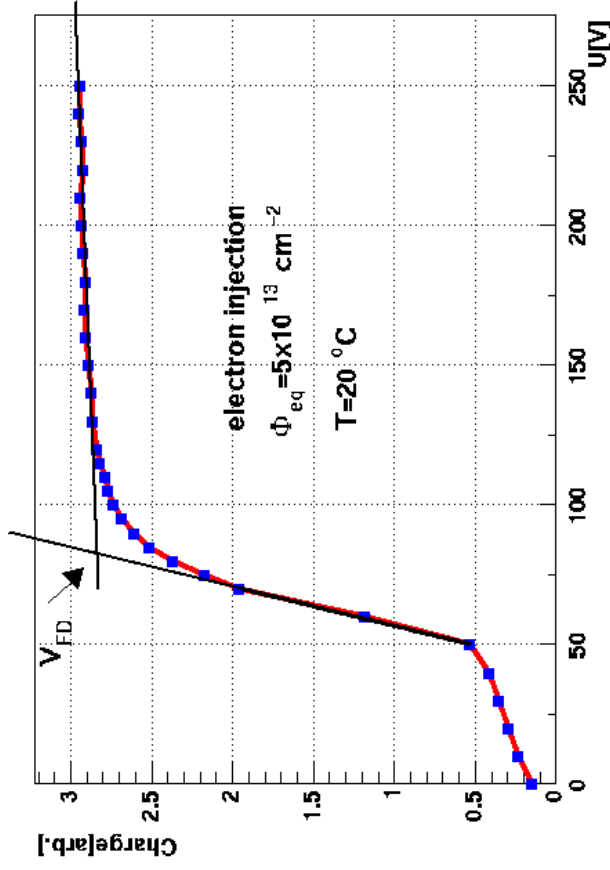
Is the above equation valid?

TCT allows to monitor space charge profile can be monitored

# IIIb. Full depletion voltage determination (IR laser)

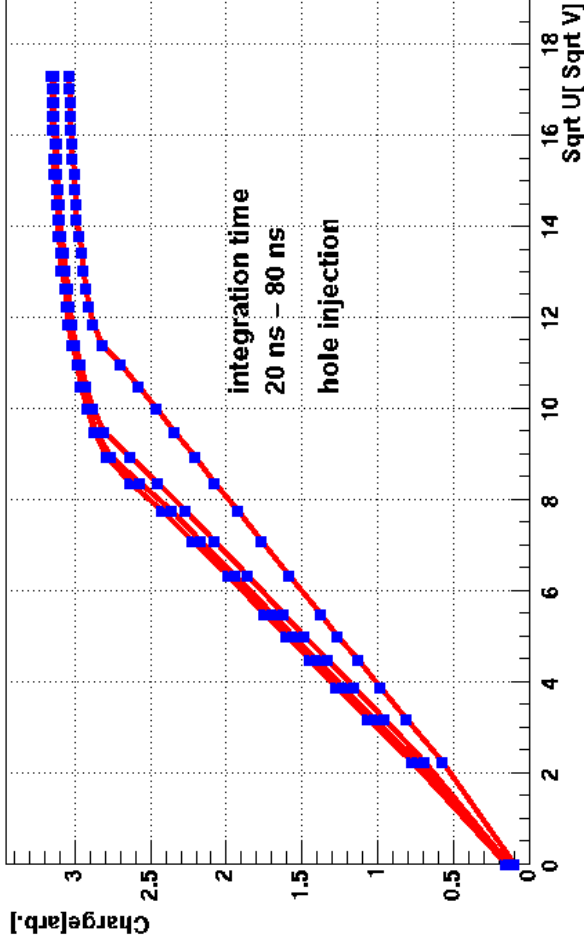
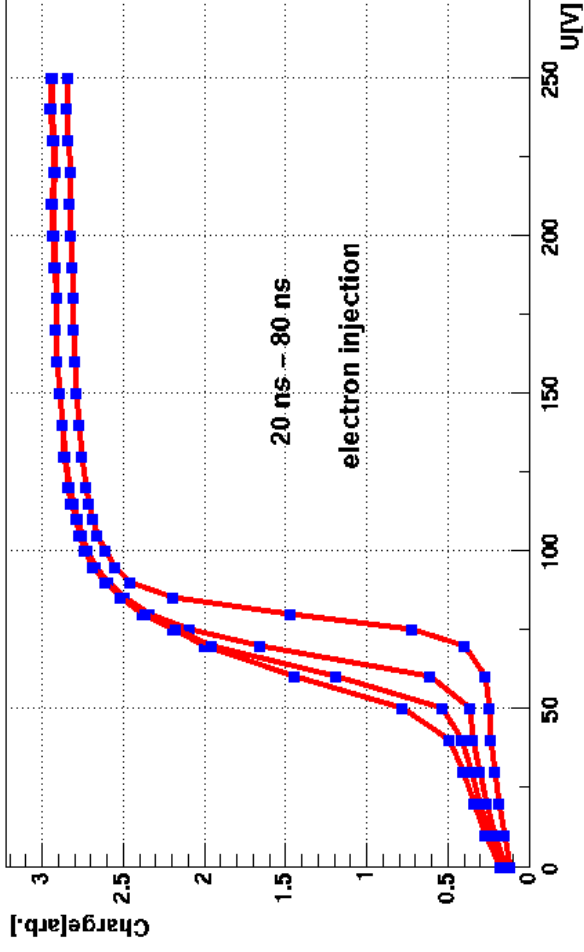


# IIIc. Full depletion voltage determination (red laser)



Steep transition at  $U \sim V_{FD}$

$$Q \propto \frac{d}{D} \Rightarrow Q \propto \sqrt{\frac{U}{V_{FD}}}$$



The QV curve depends on integration time!  
 Above 40 ns this dependence becomes less important  
 if  $V_{FD} >$  few tens Volts

## Ile. Full depletion voltage determination

### Checking the electric field profile in the detector

Hole injection in irradiated  
silicon pad detector:

$$Q = Q_h \propto \frac{d}{D} \propto \sqrt{\frac{U}{V_{FD}}}$$

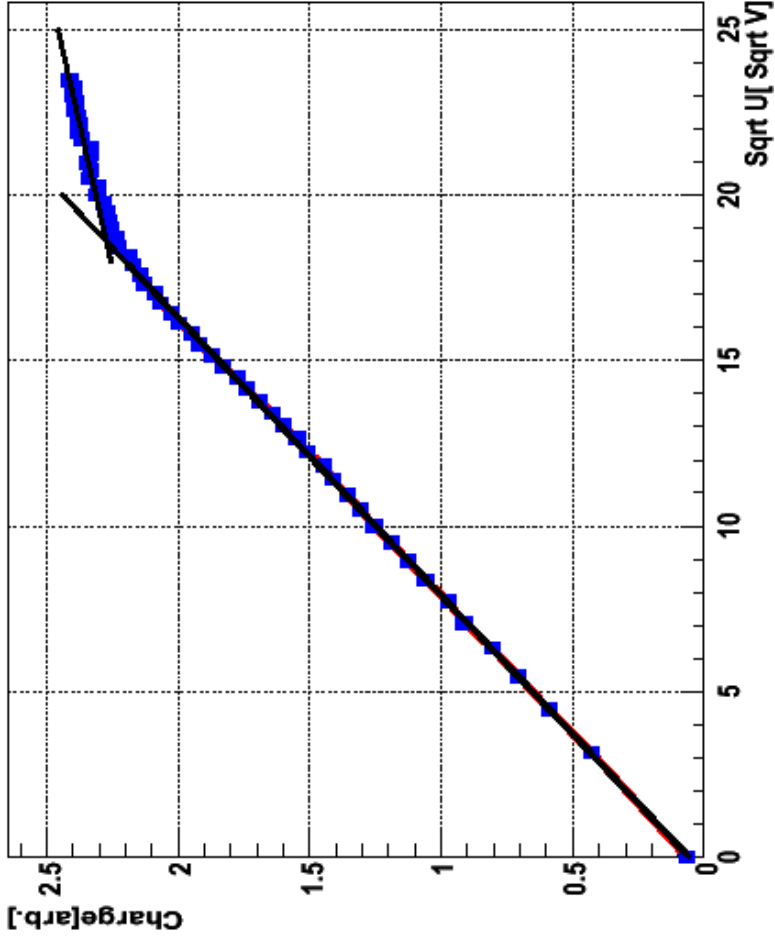
Only the carriers drifting in the depleted region contribute to the current. (diffusion of carriers through the undepleted high ohmic resistant bulk is slow - not included in the integral window of 60 ns)

A silicon material with high initial resistivity is used ( $V_{FD} \sim 10$  V before irradiation) to reduce importance of initial impurities!



The effect of shallow levels is therefore minimized!

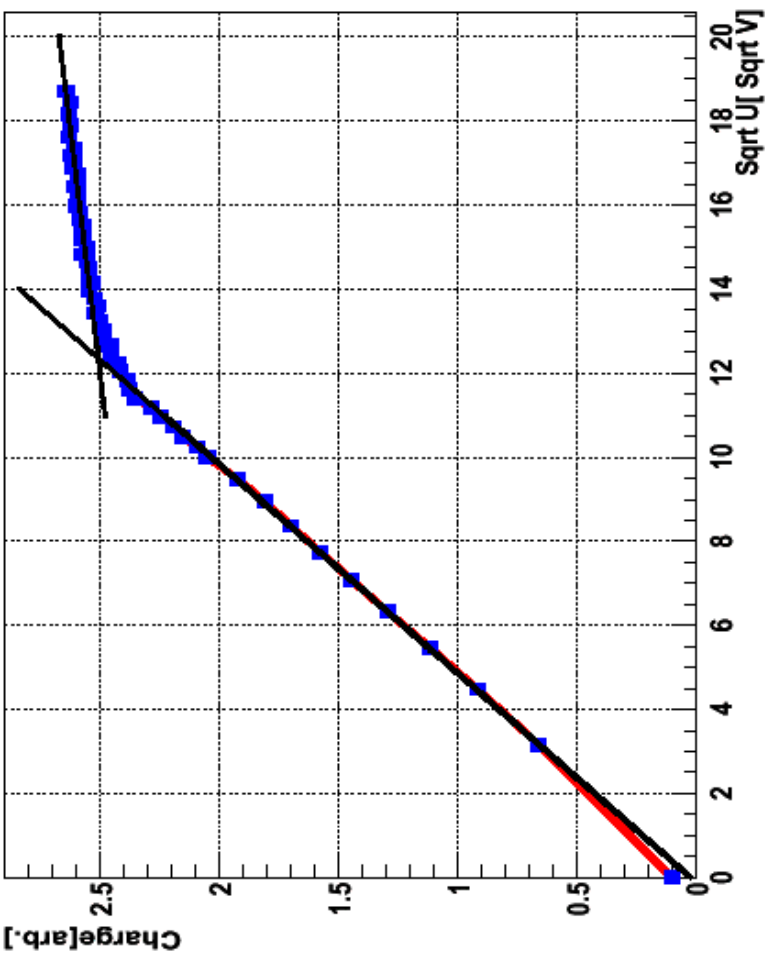
*Standard material  
irradiated with neutrons:*



$$\Phi_{\text{eq}} = 2 \times 10^{14} \text{ cm}^{-2}, V_{FD} = 295 \text{ V}$$

$$N_{\text{eff}} \approx \text{const.}$$

*Oxygenated material  
irradiated with neutrons:*

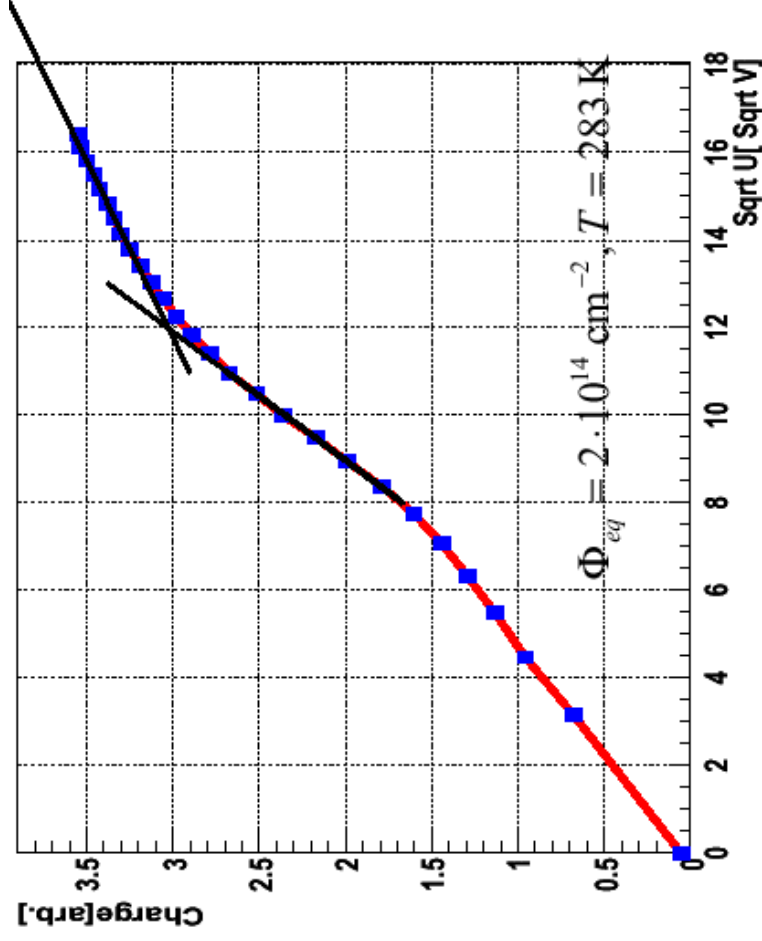


$$\Phi_{\text{eq}} = 7.5 \times 10^{13} \text{ cm}^{-2}, V_{FD} = 105 \text{ V}$$

$$N_{\text{eff}} \approx \text{const.}$$



**Oxygenated material irradiated  
with protons to high fluence**

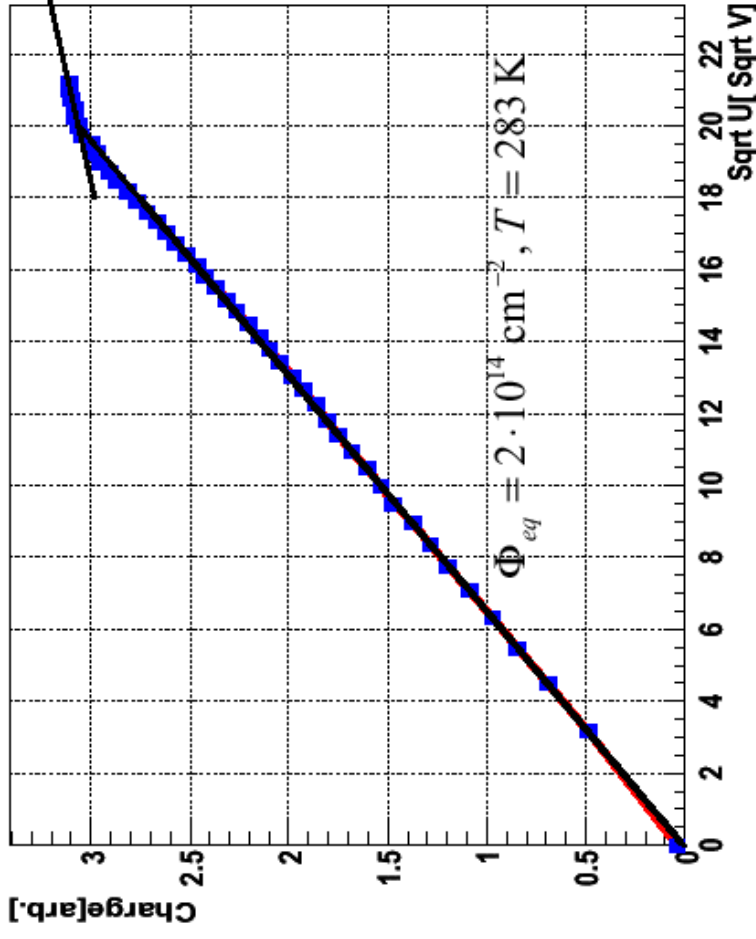


$N_{eff} \neq \text{const.}$



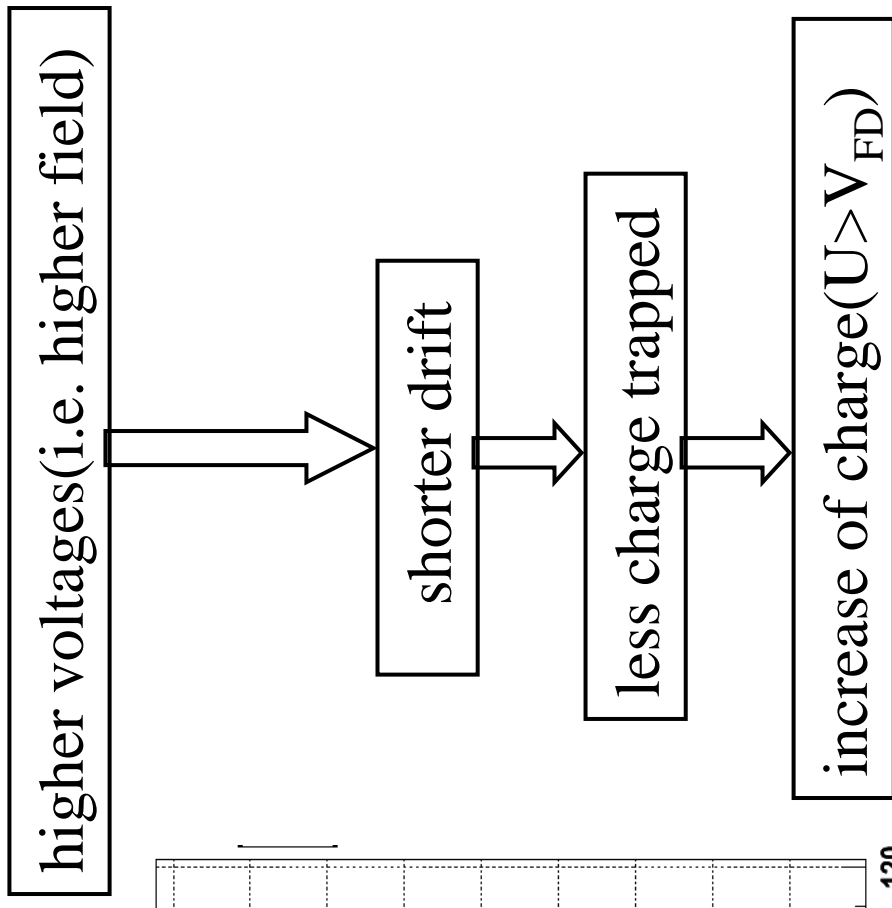
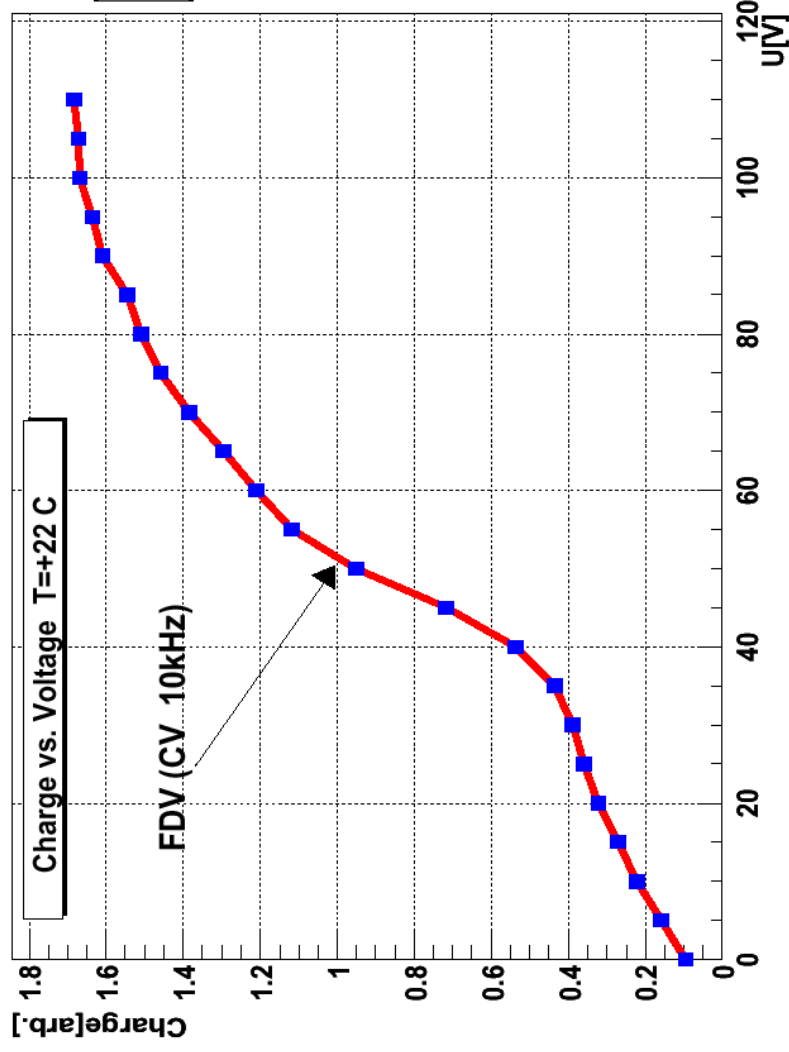
Shape of the so called:  
"double junction"

**Standard material irradiated  
with protons to high fluence**



$N_{eff} \approx \text{const.}$

# IIIa. Effective carrier trapping time determination



## IIIb. Effective carrier trapping time determination

induced current after  
instant carrier  
injection in pad  
detector-diode

$$I_{e,h}(t) = e_0 \overbrace{N_{e,h}(t)}^{q(t)} \frac{1}{D} v_{e,h}(t)$$

decrease of the  
amount of the drifting  
charge

$$N_{e,h}(t) = N_{e,h}(0) \exp\left(\frac{-t}{\tau_{\text{eff},e,h}}\right)$$

$$I_{e,h}(t) = \left[ e_0 N_{e,h}(0) \frac{1}{D} v_{e,h}(t) \right] \exp\left(\frac{-t}{\tau_{\text{eff},e,h}}\right)$$

# IIIc. Effective carrier trapping time

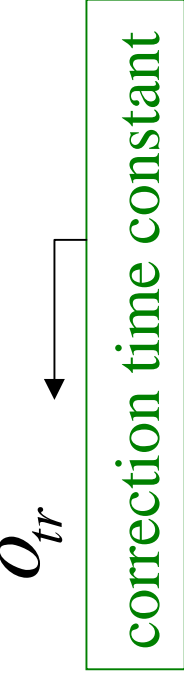
## determination

trapping

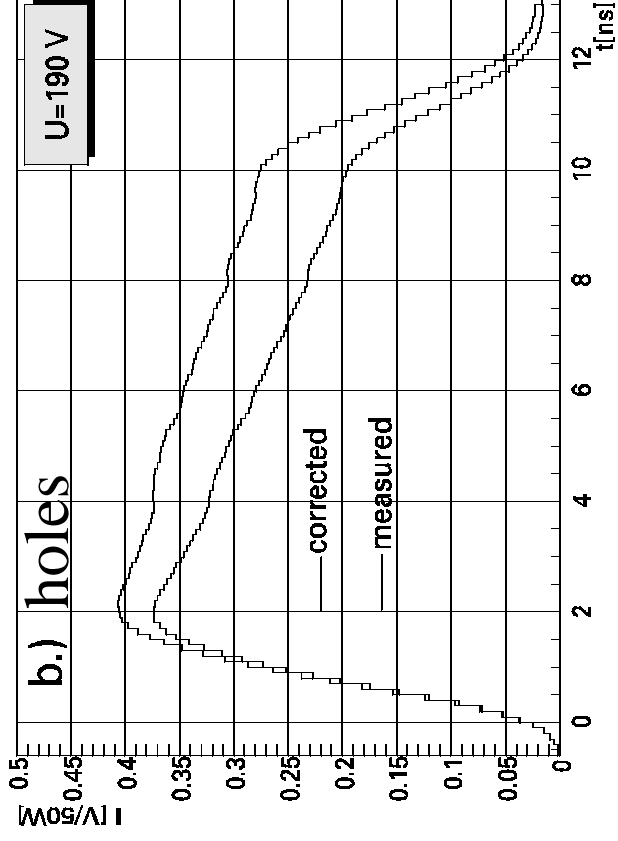
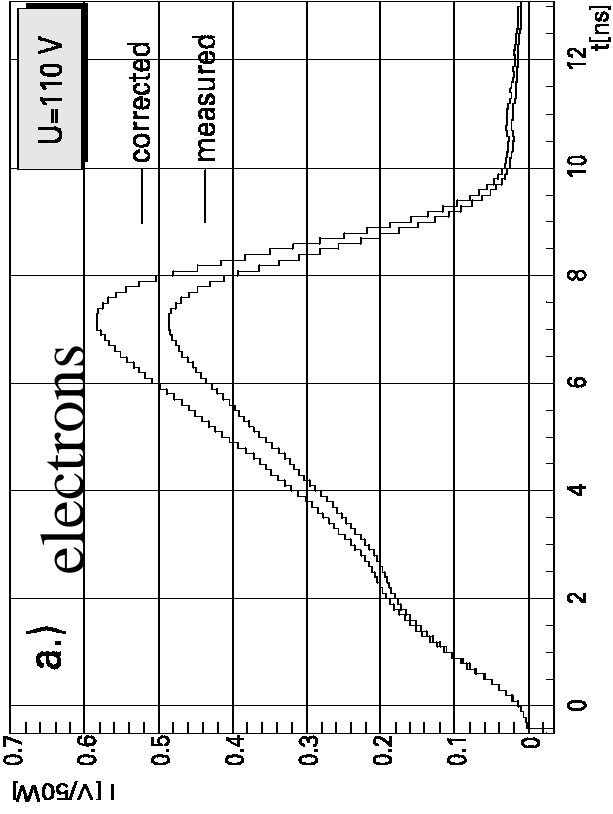
correction:

$$I_c(t) = I_m(t) \exp\left(-\frac{t-t_0}{\hat{\theta}_{tr}}\right)$$

start of the laser pulse



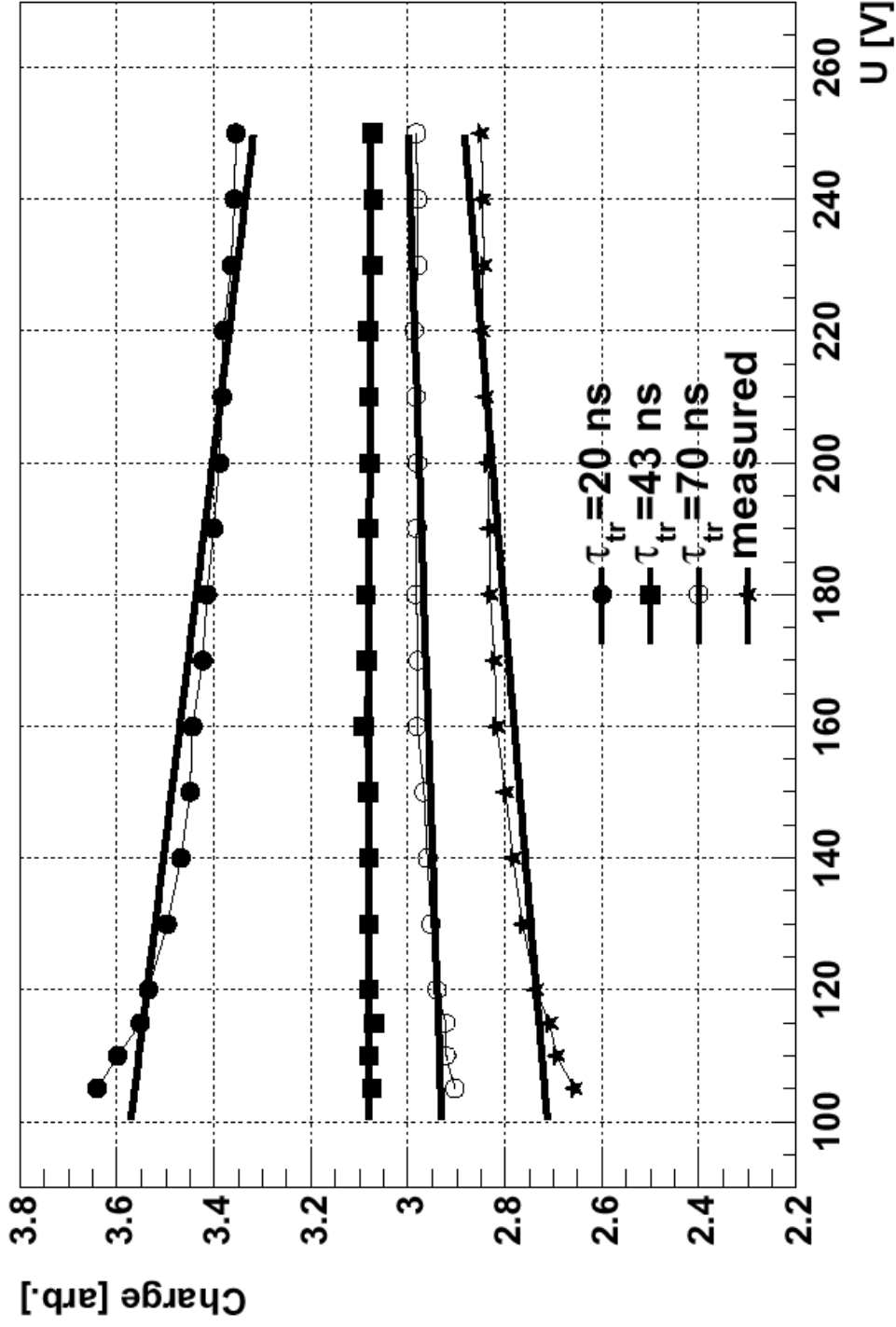
**corrected current**



# III.d. Effective carrier trapping time determination

$\tau_{eff} = \tau_{tr}$  that gives equal current integral above  $V_{FD}$   
 (compensate the trapping)

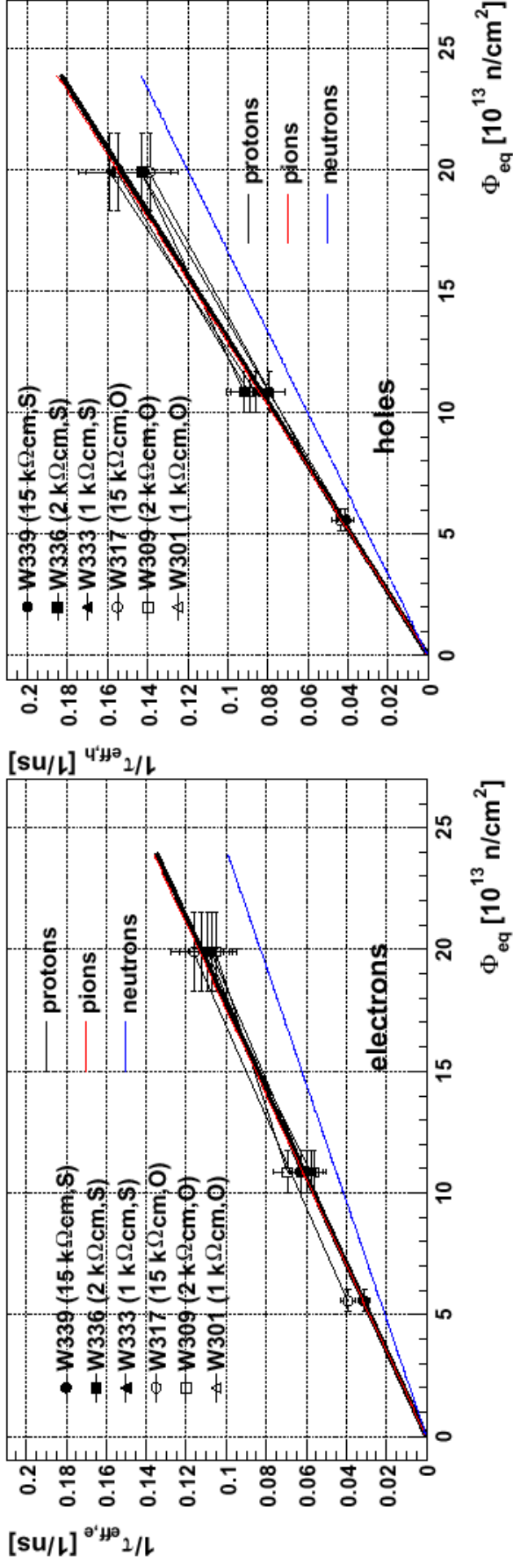
Corrected charge



$\tau_{tr} > \tau_{eff}$  - lower voltages are under weighted

CCE can be determined from the corrected charge and measured charge ratio!!

## IIIe. Effective carrier trapping time determination

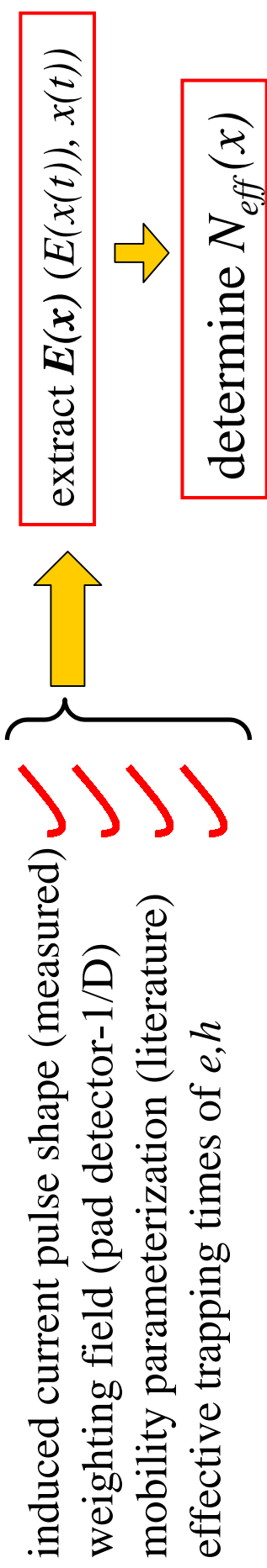


T=-10°C	$\beta_e$ [ $10^{-16}$ cm <sup>2</sup> /ns]	$\beta_e$ [ $10^{-16}$ cm <sup>2</sup> /ns]
reactor neutrons	4.1±0.1 (~5-8)	6.0±0.2 (~2-3)
pions	5.7±0.2	7.7±0.2
protons	5.6±0.2	7.7±0.2

$$\frac{1}{\tau_{eff, e, h}} = \beta_{e, h}(t, T) \Phi_{eq}$$

Different material were studied in terms of: **oxygen content**, carbon content, **initial resistivity**, **different silicon wafer producers and manufacturers (topsil-BNL, wacker-STM)**

## IVa. Electric field profile in the detector (diode)



$$I_{e,h}(t) = N_0 \exp\left(\frac{-t}{\tau_{eff_{e,h}}}\right) \frac{1}{D} v_{e,h}(t)$$

$$x_{e,h}(t) = \int_{t_0}^t I_{e,h}(t') \frac{D}{N_0} \exp\left(\frac{t'}{\tau_{eff_{e,h}}}\right) dt' \Rightarrow D = x_{e,h}(t_t)$$

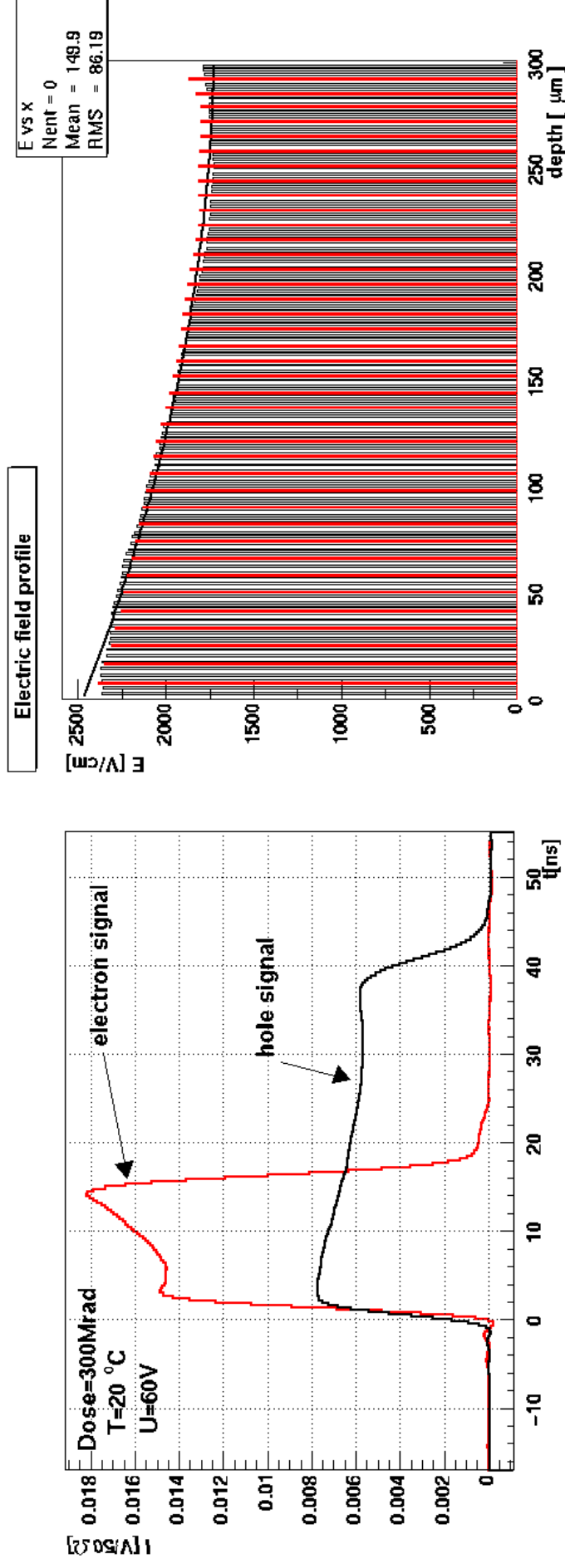
$$v_{e,h}(t) = \mu_{e,h}(E(t)) E(t) = I_{e,h}(t) \frac{D}{N_0} \exp\left(\frac{t}{\tau_{eff_{e,h}}}\right)$$

○ input-meas.  
 parameters

○ unknown  
 parameters

More reliable determination from holes signals  
 (longer signal, less influence of laser width)!

## IVb. Electric field profile in the detector (diode)



measured TCT pulse shapes

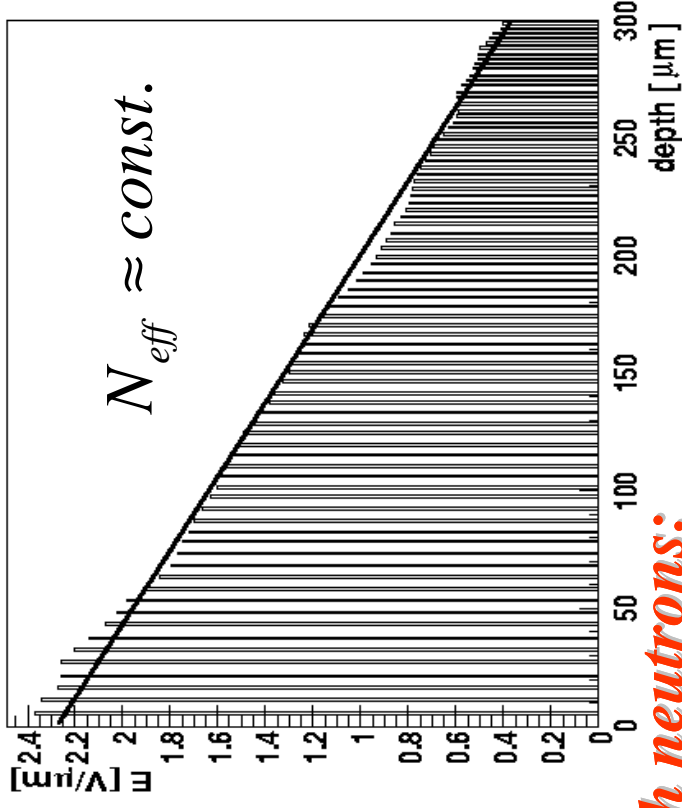
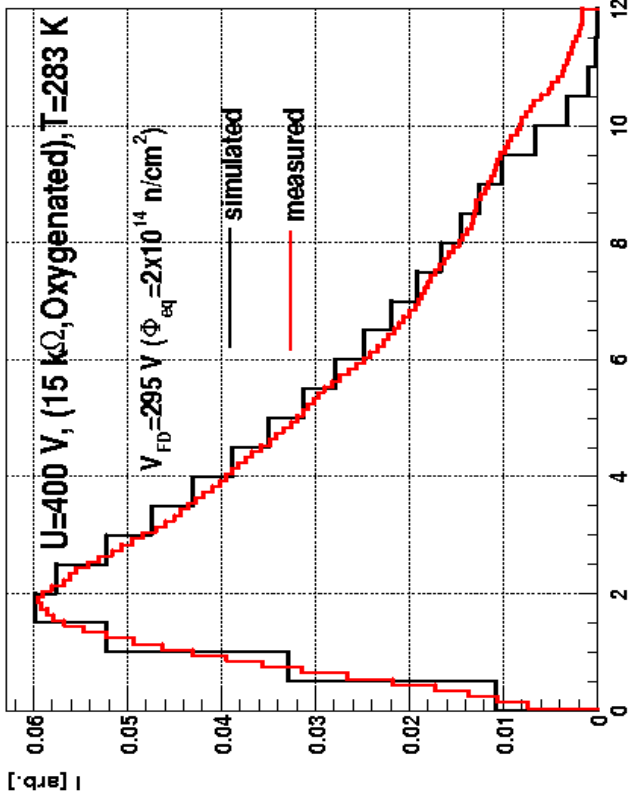
electric field profile  
obtained from meas.

Improvements to be done:

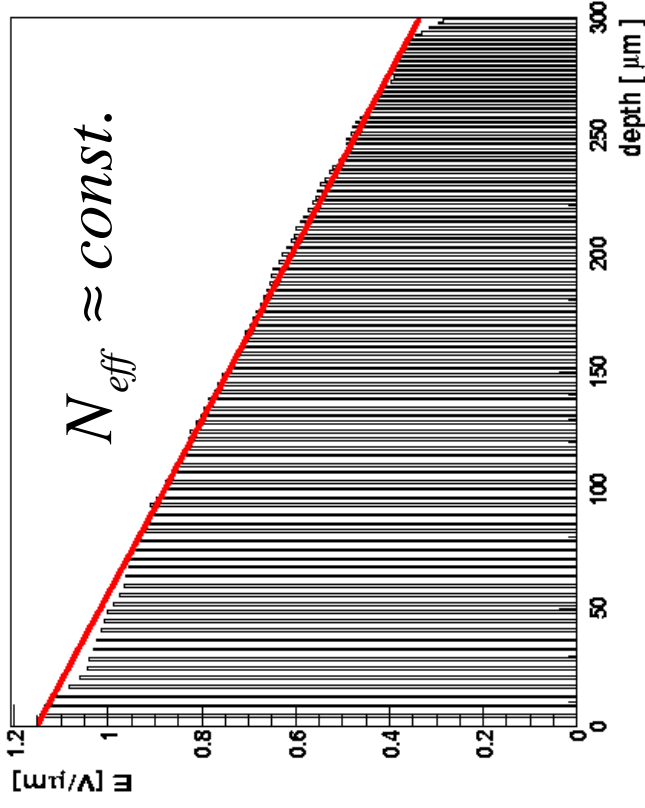
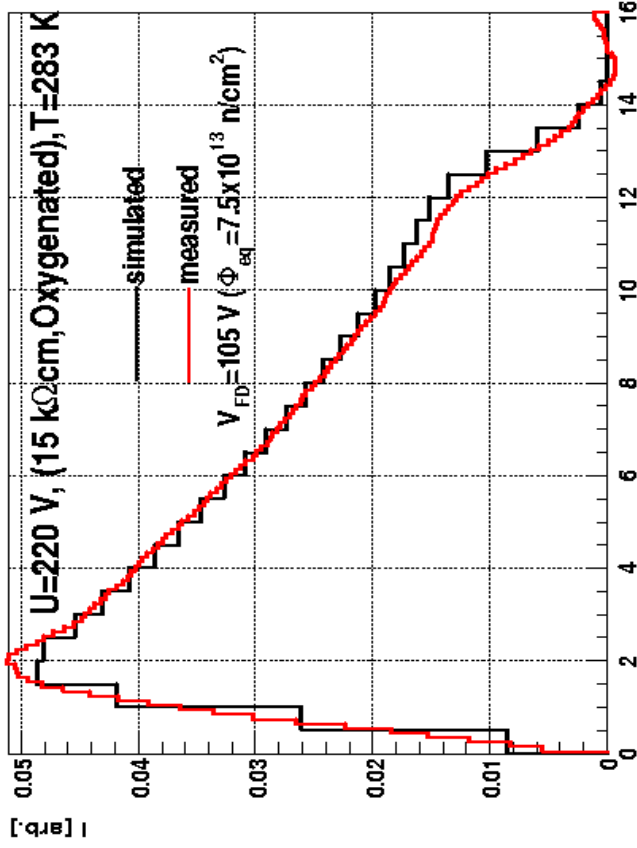
- deconvolution of measured current for laser pulse to be taken into account!
- choice of  $t_c$  is to some extent (of order  $\sim 1$  ns) arbitrary!



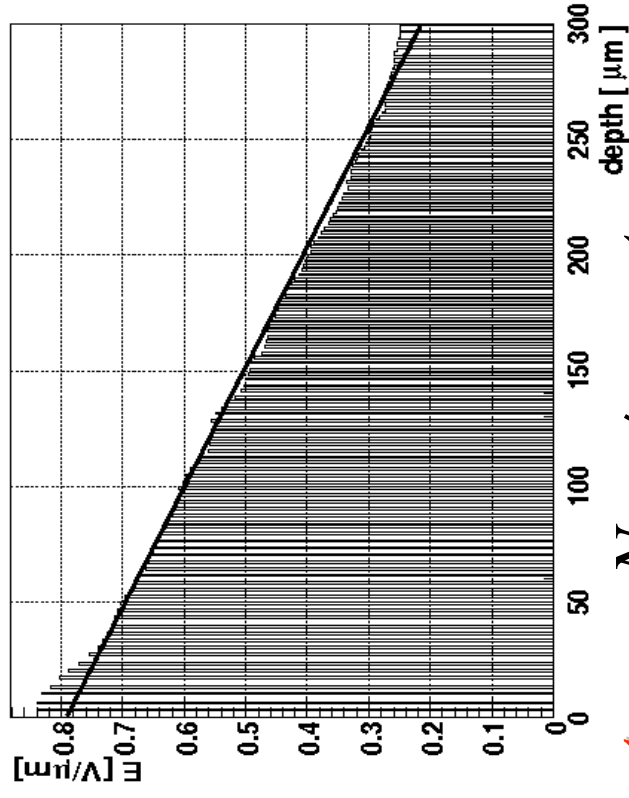
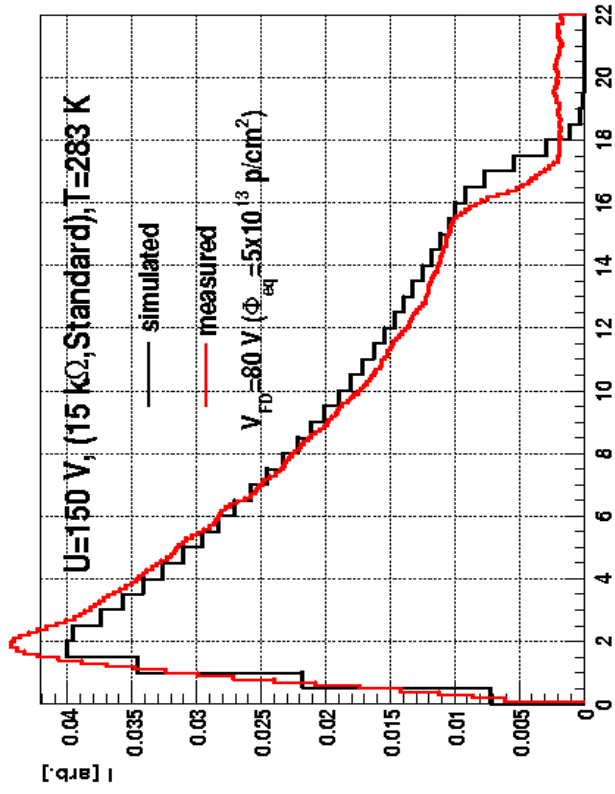
## Standard material irradiated with neutrons:



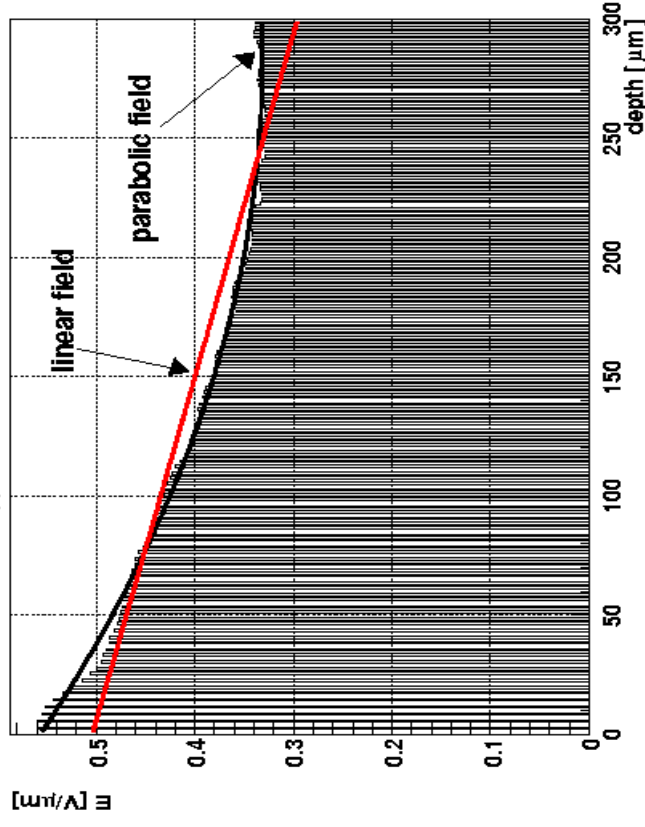
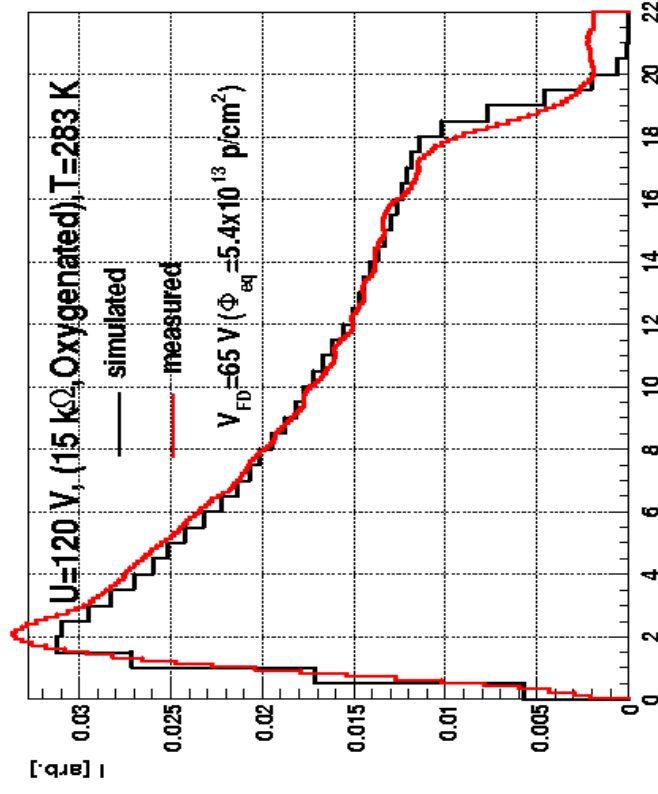
## Oxygenated material irradiated with neutrons:



**Standard material irradiated with protons:  $N_{eff} \approx const.$**

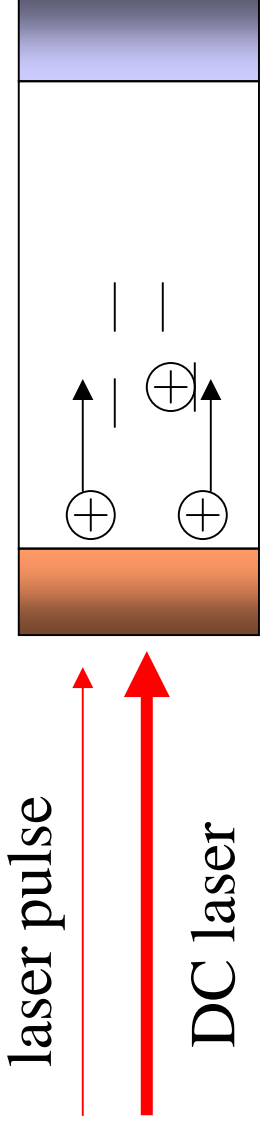


**Oxygenated material irradiated with protons:  $N_{eff} \neq const.$**



# Va. Defect characterization

Observation of TCT signals at different  $T$  and presence of continuous illumination!



$$p = \frac{\Delta I}{S v_h e_0}$$

Increase of leakage current due to illumination

drift time of holes through the detector

$N_{eff}$  controlled by:

- illumination intensity ( $p$ )
- operation voltage ( $p$ )
- temperature (trapping -detrapping process)

capture

emission

$$\frac{dp_t}{dt} = c_p p [P_t - p_t] - e_p p_t$$

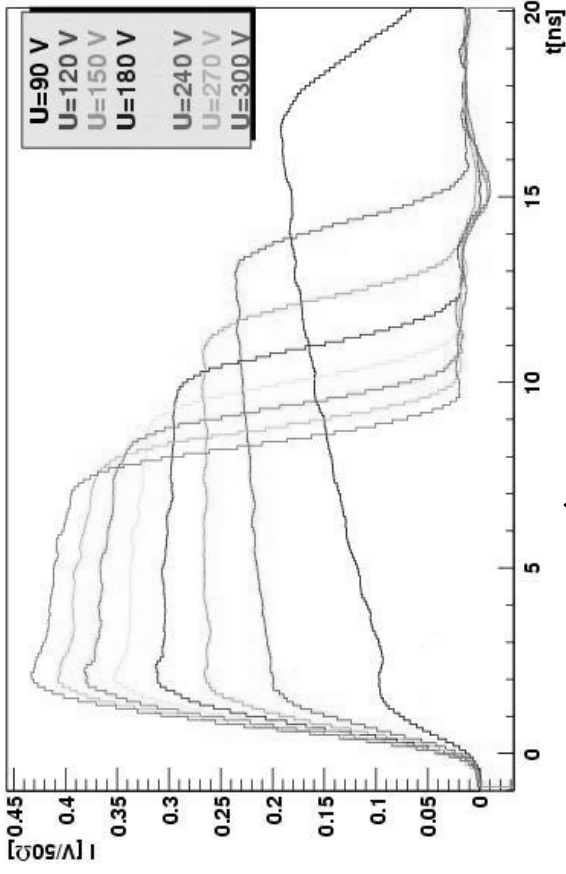
concentration of free traps

$$p_t(t) = c_p p P_t \tau_{td,p} \left[ 1 - \exp\left(-\frac{t}{\tau_{td,p}}\right) \right]$$

$$\tau_{td,p} = (c_p p + e_p)^{-1}$$

$$t \rightarrow \infty \rightarrow N_{eff}(T, p) = N_{eff,0} + P_{t\infty}(E_t, p, T)$$

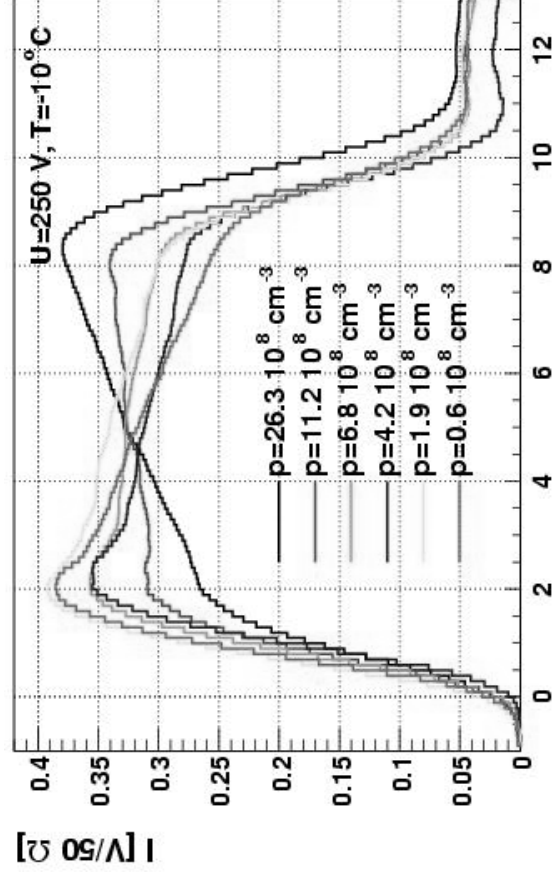
# Vb. Defect characterization (steady state)



**Hole injection!**

$\Phi_{eq} = 5 \times 10^{13} \text{ cm}^{-3}$   
*different voltages*  
 $p = 2-14 \times 10^8 \text{ cm}^{-3}$   
 $T = 263 \text{ K}$

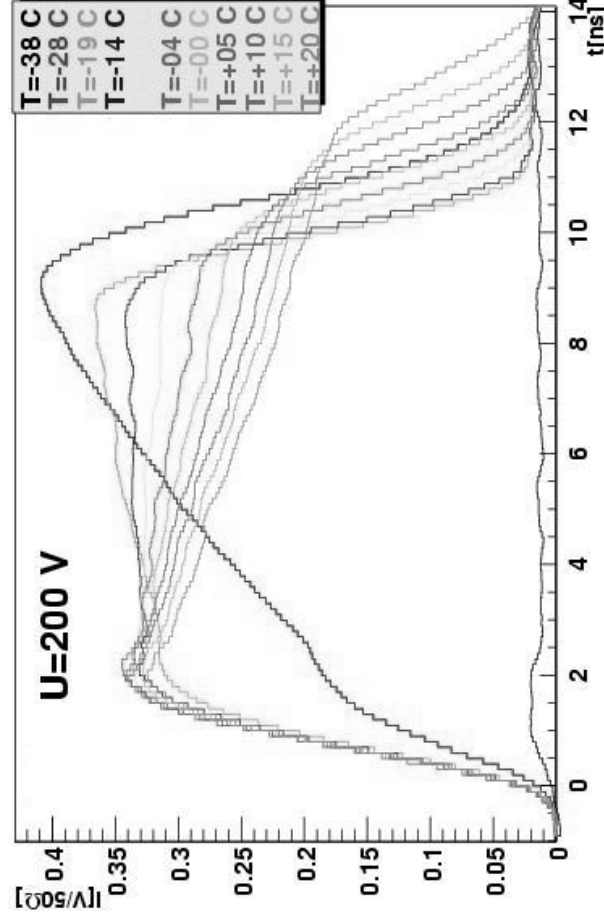
*different temperatures* →  
 $p \sim 3 \times 10^8 \text{ cm}^{-3}$



←

**Hole injection!**  
 $\Phi_{eq} = 7.5 \times 10^{13} \text{ cm}^{-3}$   
*different light intensities*

$T = 263 \text{ K}, U = 180 \text{ V}$

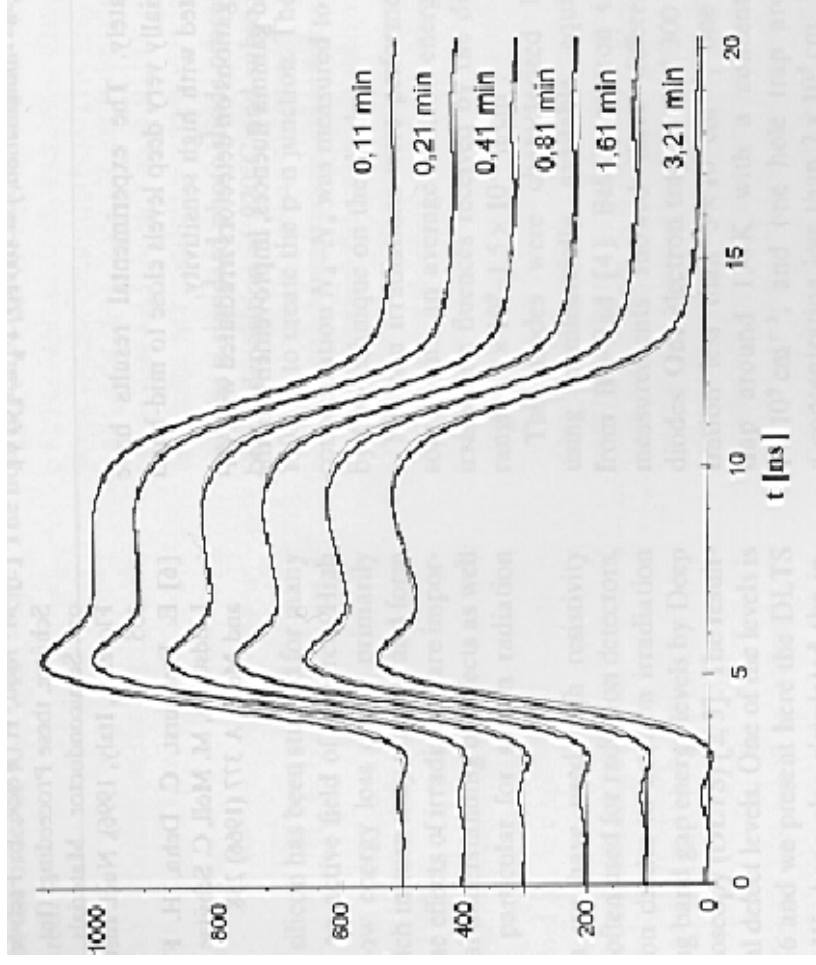


**$N_{eff}$  can be estimated from the slope of the signal!**

## Vc. Defect characterization (transient analysis)

Transient analysis:

E. Fretwurst et al. NIMA 388,p. 356



trap filling and change of  
electric field



from fits to measured  
signals one can obtain

effective dopant  
concentration

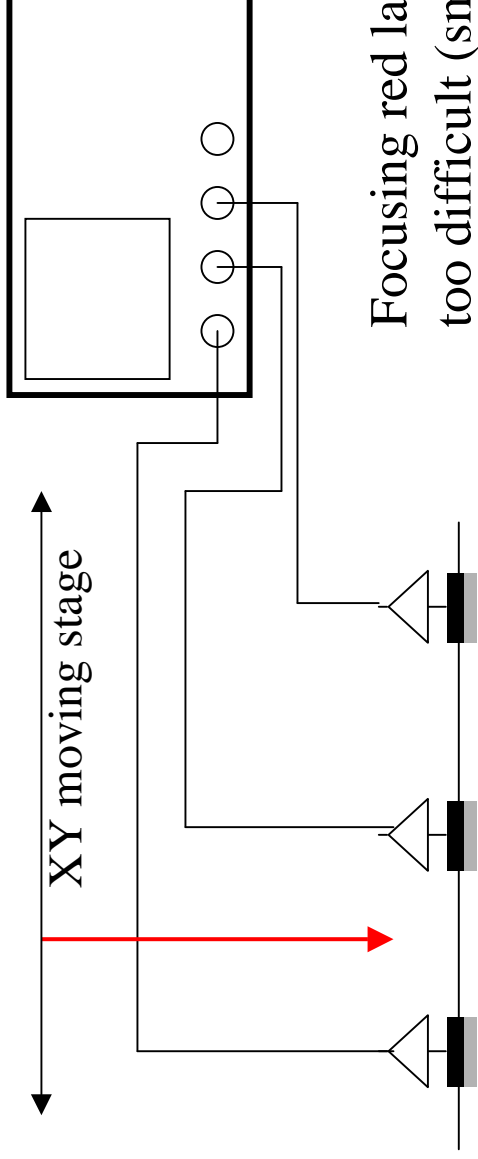


parameters ( $\sigma_{e,h}$ ,  $P_t$ ) of  
traps can be extracted

transient analysis at different T has to  
be performed to reveal different traps

## VI. Charge collection in segmented devices (FUTURE WORK)

$E_w$  depends on geometry of segmented (multi electrode) devices and causes different signal formation properties as expected from simple planar diodes!



Focusing red laser to few mm is not too difficult (small penetration depth)

Main problem:  
to simulate mip particles  
narrow cone IR laser is needed !

**\_\_\_\_\_**  
b + U

### Potential interest:

- study of transfer coefficients for silicon detectors with intermediate strips
- charge sharing between electrodes induced by charge trapping
- study of electric field profile (dead pockets)

## *Conclusions*

A TCT is a powerful and yet simple tool to investigate large number of silicon detector properties!

Crucial building blocks of a TCT set-up are:

- short laser pulse (driver, red, IR)
- fast amplifier and fast oscilloscope + good cabling
- cryostat

A review of various measurement quantities mostly related to measurements of irradiated detectors are given:

- sign of the space charge
- voltage of full depletion
- determination of effective trapping times
- extraction of electric field profile
- usage of TCT to determine the properties of traps